

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT application of)

Nobuo AOI)

Attention: Applications Branch

Serial No. 09/809,043)

Filed: March 16, 2001)

For: INTERLAYER DIELECTRIC)

FILM, AND METHOD FOR)

FORMING THE SAME AND)

INTERCONNECTION)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on _____



PRELIMINARY AMENDMENT

Honorable Commissioner of Patents and Trademarks

Washington, D.C. 20231

Sir:

Please preliminary amend the subject application as follows:

In the Specification:

Please amend the specification as follows:

Page 19, Line 11

91 FIG. 2B is a view illustrating a structure of a second cross-linking molecule used in Example [2] 1 of the method for forming an interlayer dielectric film of the first embodiment.

Page 20 continuing on page 21, line 24

92 FIGS. [13A] 12A through [13C] 12C are views illustrating steps of a method for forming an interconnection of the third embodiment.

Page 21, line 2

93 FIGS. [14A] 13A and [14B] 13B are views illustrating steps of the method for forming an interconnection of the third embodiment.